ABSTRACT

A NEW PROCESS OF DUAL DAMASCENE STRUCTURE

A method for forming a dual damascene "T" shaped interconnect by first forming a "T" shaped temporary post, than forming an insulating layer around the top part of the post, than removing the material contained within the post to form a "T" shaped opening and refilling the opening with copper after which the metal surface is planarized using Chemical Mechanical Planarization.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)